

PCB Specification

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Company: SKA SA
Billing Address: 17 Baker St, Rosebank, Johannesburg, South Africa
PO Box 522940, Saxonwold, 2132
Postal Address: SKA SA, 3rd Floor, The Park, Park Road, Pinelands, 7405, South Africa
Contact: David George Email: david.george@ska.ac.za
Tel: +27 11 442 2434
Philip Gibbs Email: philip.gibbs@ska.ac.za
Tel: +27 21 506 7363

Board name: **SFP+ Mezzanine Card**
Revision: **0**
Release: **PRELIM**

PCB Details

<i>PCB Specifications:</i>	IPC 6012 Class 2
<i>Finished Board Size:</i>	90 x 107.4 mm
<i>PCB Type:</i>	Multi-layer
<i>Layer Count:</i>	8
<i>Dielectric:</i>	All dielectric layers to be Isola 370HR high temperature laminate
<i>Nominal board Thickness:</i>	1.6mm; tolerance +/-10%
<i>Hole tolerance:</i>	+3mil for vias; +/- 3mil for component holes and slots
<i>Finish:</i>	ENIG
<i>Soldermask:</i>	Green
<i>Silkscreen:</i>	White
<i>Minimum clearance:</i>	4 mil in BGA areas, 6 mil otherwise
<i>Handling rails:</i>	TBD
<i>Panelisation:</i>	TBD

PCB Stackup

Layer	#	Copper (oz)	Dielectric (mil)**	Filename
Pastemask Top		-	-	sfpp.GTP
Silkscreen Top		-	-	sfpp.GTO
Soldermask Top		-	-	sfpp.GTS
Signal Top	1	0.5		sfpp.GTL
			5mil	
Ground 1	2	0.5		sfpp.GP1
			8mil	
Signal 1	3	0.5		sfpp.G1
			8mil	
Power 1	4	0.5		sfpp.GP2
			*	
Power 2	5	0.5		sfpp.G2
			8mil	
Signal 2	6	0.5		sfpp.GP3
			8mil	
Ground 2	7	0.5		sfpp.GP4
			5mil	
Signal Bottom	8	0.5		sfpp.GBL
Soldermask Bottom		-	-	sfpp.GBS
Silkscreen Bottom		-	-	sfpp.GBO
Pastemask Bottom		-	-	sfpp.GBP

* Thickness may be adjusted to achieve nominal total thickness previously specified, to satisfy impedance targets and to accommodate manufacturing processes.

Impedance Controlled Traces

All impedance matching to +/- 10%

Microstrip

Layers:	Signal Top (#1), Signal Bottom (#8)
Target Impedance:	50 ohm
Trace thickness:	8 mil